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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	2
Number of Macrocells	32
Number of Gates	600
Number of I/O	36
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7032slc44-7

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Table 2. MAX	7000S Device I	Features -				
Feature	EPM7032S	EPM7064S	EPM7128S	EPM7160S	EPM7192S	EPM7256S
Usable gates	600	1,250	2,500	3,200	3,750	5,000
Macrocells	32	64	128	160	192	256
Logic array blocks	2	4	8	10	12	16
Maximum user I/O pins	36	68	100	104	124	164
t _{PD} (ns)	5	5	6	6	7.5	7.5
t _{SU} (ns)	2.9	2.9	3.4	3.4	4.1	3.9
t _{FSU} (ns)	2.5	2.5	2.5	2.5	3	3
t _{CO1} (ns)	3.2	3.2	4	3.9	4.7	4.7
f _{CNT} (MHz)	175.4	175.4	147.1	149.3	125.0	128.2

...and More Features

- Open-drain output option in MAX 7000S devices
- Programmable macrocell flipflops with individual clear, preset, clock, and clock enable controls
- Programmable power-saving mode for a reduction of over 50% in each macrocell
- Configurable expander product-term distribution, allowing up to 32 product terms per macrocell
- 44 to 208 pins available in plastic J-lead chip carrier (PLCC), ceramic pin-grid array (PGA), plastic quad flat pack (PQFP), power quad flat pack (RQFP), and 1.0-mm thin quad flat pack (TQFP) packages
- Programmable security bit for protection of proprietary designs
- 3.3-V or 5.0-V operation
 - MultiVoltTM I/O interface operation, allowing devices to interface with 3.3-V or 5.0-V devices (MultiVolt I/O operation is not available in 44-pin packages)
 - Pin compatible with low-voltage MAX 7000A and MAX 7000B devices
- Enhanced features available in MAX 7000E and MAX 7000S devices
 - Six pin- or logic-driven output enable signals
 - Two global clock signals with optional inversion
 - Enhanced interconnect resources for improved routability
 - Fast input setup times provided by a dedicated path from I/O pin to macrocell registers
 - Programmable output slew-rate control
- Software design support and automatic place-and-route provided by Altera's development system for Windows-based PCs and Sun SPARCstation, and HP 9000 Series 700/800 workstations

- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest
- Programming support
 - Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices
 - The BitBlasterTM serial download cable, ByteBlasterMVTM parallel port download cable, and MasterBlasterTM serial/universal serial bus (USB) download cable program MAX 7000S devices

General Description

The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2.* See Table 3 for available speed grades.

Device	Speed Grade									
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20
EPM7032		✓	✓		✓		✓	✓	✓	
EPM7032S	✓	✓	✓		✓					
EPM7064		✓	✓		~		✓	✓		
EPM7064S	✓	✓	✓		~					
EPM7096			✓		~		✓	✓		
EPM7128E			✓	✓	~		✓	✓		✓
EPM7128S		✓	✓		~			✓		
EPM7160E				✓	✓		✓	✓		✓
EPM7160S		✓	✓		~			✓		
EPM7192E						✓	✓	✓		✓
EPM7192S			✓		✓			✓		
EPM7256E						✓	✓	✓		✓
EPM7256S			✓		✓			✓		

The MAX 7000 architecture supports 100% TTL emulation and high-density integration of SSI, MSI, and LSI logic functions. The MAX 7000 architecture easily integrates multiple devices ranging from PALs, GALs, and 22V10s to MACH and pLSI devices. MAX 7000 devices are available in a wide range of packages, including PLCC, PGA, PQFP, RQFP, and TQFP packages. See Table 5.

Table 5. M.	AX 7000) Maxim	um Use	r I/O Pii	ıs N	ote (1)						
Device	44- Pin PLCC	44- Pin PQFP	44- Pin TQFP	68- Pin PLCC	84- Pin PLCC	100- Pin PQFP	100- Pin TQFP	160- Pin PQFP	160- Pin PGA	192- Pin PGA	208- Pin PQFP	208- Pin RQFP
EPM7032	36	36	36									
EPM7032S	36		36									
EPM7064	36		36	52	68	68						
EPM7064S	36		36		68		68					
EPM7096				52	64	76						
EPM7128E					68	84		100				
EPM7128S					68	84	84 (2)	100				
EPM7160E					64	84		104				
EPM7160S					64		84 (2)	104				
EPM7192E								124	124			
EPM7192S								124				
EPM7256E								132 (2)		164		164
EPM7256S											164 (2)	164

Notes:

- When the JTAG interface in MAX 7000S devices is used for either boundary-scan testing or for ISP, four I/O pins become JTAG pins.
- (2) Perform a complete thermal analysis before committing a design to this device package. For more information, see the Operating Requirements for Altera Devices Data Sheet.

MAX 7000 devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000 architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of EPM7032, EPM7064, and EPM7096 devices.

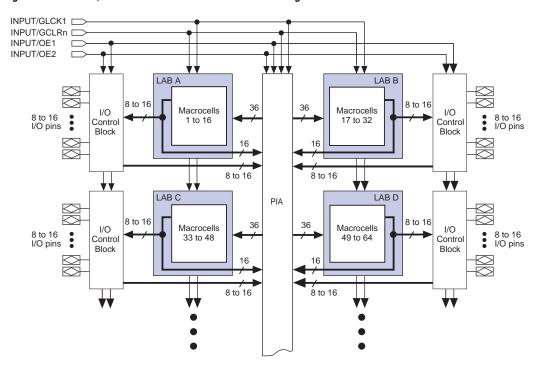


Figure 1. EPM7032, EPM7064 & EPM7096 Device Block Diagram

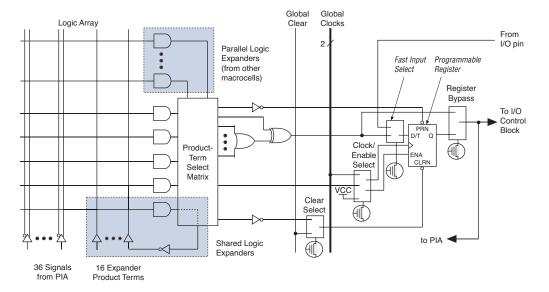
Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for MAX 7000E and MAX 7000S devices

Macrocells

The MAX 7000 macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7064, and EPM7096 devices is shown in Figure 3.

Figure 3. EPM7032, EPM7064 & EPM7096 Device Macrocell



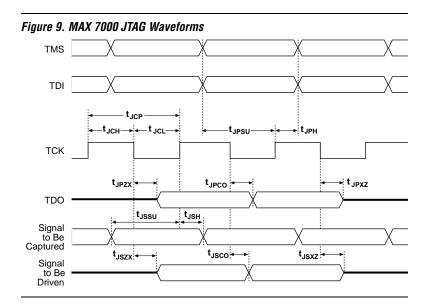


Figure 9 shows the timing requirements for the JTAG signals.

Table 12 shows the JTAG timing parameters and values for MAX 7000S devices.

Table 1	2. JTAG Timing Parameters & Values for MAX 70	00S De	vices	
Symbol	Parameter	Min	Max	Unit
t _{JCP}	TCK clock period	100		ns
t _{JCH}	TCK clock high time	50		ns
t _{JCL}	TCK clock low time	50		ns
t _{JPSU}	JTAG port setup time	20		ns
t _{JPH}	JTAG port hold time	45		ns
t _{JPCO}	JTAG port clock to output		25	ns
t _{JPZX}	JTAG port high impedance to valid output		25	ns
t _{JPXZ}	JTAG port valid output to high impedance		25	ns
t _{JSSU}	Capture register setup time	20		ns
t _{JSH}	Capture register hold time	45		ns
t _{JSCO}	Update register clock to output		25	ns
t _{JSZX}	Update register high impedance to valid output		25	ns
t _{JSXZ}	Update register valid output to high impedance		25	ns



For more information, see *Application Note* 39 (*IEEE 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices*).

Operating Conditions

Tables 13 through 18 provide information about absolute maximum ratings, recommended operating conditions, operating conditions, and capacitance for 5.0-V MAX 7000 devices.

Table 1	Table 13. MAX 7000 5.0-V Device Absolute Maximum Ratings Note (1)												
Symbol	Parameter	Conditions	Min	Max	Unit								
V _{CC}	Supply voltage	With respect to ground (2)	-2.0	7.0	V								
VI	DC input voltage		-2.0	7.0	V								
I _{OUT}	DC output current, per pin		-25	25	mA								
T _{STG}	Storage temperature	No bias	-65	150	° C								
T _{AMB}	Ambient temperature	Under bias	-65	135	° C								
TJ	Junction temperature	Ceramic packages, under bias		150	°C								
		PQFP and RQFP packages, under bias		135	°C								

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CCINT}	Supply voltage for internal logic and input buffers	(3), (4), (5)	4.75 (4.50)	5.25 (5.50)	V
V _{CCIO}	Supply voltage for output drivers, 5.0-V operation	(3), (4)	4.75 (4.50)	5.25 (5.50)	V
	Supply voltage for output drivers, 3.3-V operation	(3), (4), (6)	3.00 (3.00)	3.60 (3.60)	V
V _{CCISP}	Supply voltage during ISP	(7)	4.75	5.25	V
V _I	Input voltage		-0.5 (8)	V _{CCINT} + 0.5	V
Vo	Output voltage		0	V _{CCIO}	V
T _A	Ambient temperature	For commercial use	0	70	°C
		For industrial use	-40	85	°C
TJ	Junction temperature	For commercial use	0	90	°C
		For industrial use	-40	105	° C
t _R	Input rise time			40	ns
t _F	Input fall time			40	ns

Notes to tables:

- (1) See the Operating Requirements for Altera Devices Data Sheet.
- (2) Minimum DC input voltage on I/O pins is –0.5 V and on 4 dedicated input pins is –0.3 V. During transitions, the inputs may undershoot to –2.0 V or overshoot to 7.0 V for input currents less than 100 mA and periods shorter than 20 ns.
- (3) Numbers in parentheses are for industrial-temperature-range devices.
- (4) V_{CC} must rise monotonically.
- (5) The POR time for all 7000S devices does not exceed 300 μs. The sufficient V_{CCINT} voltage level for POR is 4.5 V. The device is fully initialized within the POR time after V_{CCINT} reaches the sufficient POR voltage level.
- (6) 3.3-V I/O operation is not available for 44-pin packages.
- (7) The V_{CCISP} parameter applies only to MAX 7000S devices.
- (8) During in-system programming, the minimum DC input voltage is –0.3 V.
- (9) These values are specified under the MAX 7000 recommended operating conditions in Table 14 on page 26.
- (10) The parameter is measured with 50% of the outputs each sourcing the specified current. The I_{OH} parameter refers to high-level TTL or CMOS output current.
- (11) The parameter is measured with 50% of the outputs each sinking the specified current. The I_{OL} parameter refers to low-level TTL, PCI, or CMOS output current.
- (12) When the JTAG interface is enabled in MAX 7000S devices, the input leakage current on the JTAG pins is typically -60 uA.
- (13) Capacitance is measured at 25° C and is sample-tested only. The OE1 pin has a maximum capacitance of 20 pF.

Figure 11 shows the typical output drive characteristics of MAX 7000 devices.

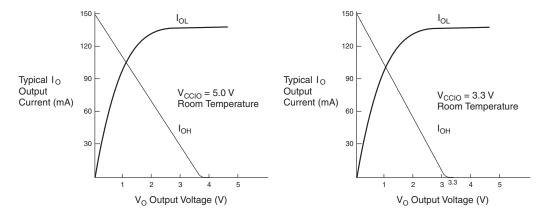


Figure 11. Output Drive Characteristics of 5.0-V MAX 7000 Devices

Timing Model

MAX 7000 device timing can be analyzed with the Altera software, with a variety of popular industry-standard EDA simulators and timing analyzers, or with the timing model shown in Figure 12. MAX 7000 devices have fixed internal delays that enable the designer to determine the worst-case timing of any design. The Altera software provides timing simulation, point-to-point delay prediction, and detailed timing analysis for a device-wide performance evaluation.

Table 2	21. MAX 7000 & MAX 7000E Ext	ernal Timing Param	eters Note	(1)						
Symbol	Parameter	Conditions		Speed Grade						
			MAX 700	0E (-10P)		000 (-10) 00E (-10)				
			Min	Max	Min	Max				
t _{PD1}	Input to non-registered output	C1 = 35 pF		10.0		10.0	ns			
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		10.0		10.0	ns			
t _{SU}	Global clock setup time		7.0		8.0		ns			
t _H	Global clock hold time		0.0		0.0		ns			
t _{FSU}	Global clock setup time of fast input	(2)	3.0		3.0		ns			
t _{FH}	Global clock hold time of fast input	(2)	0.5		0.5		ns			
t _{CO1}	Global clock to output delay	C1 = 35 pF		5.0		5	ns			
t _{CH}	Global clock high time		4.0		4.0		ns			
t _{CL}	Global clock low time		4.0		4.0		ns			
t _{ASU}	Array clock setup time		2.0		3.0		ns			
t _{AH}	Array clock hold time		3.0		3.0		ns			
t _{ACO1}	Array clock to output delay	C1 = 35 pF		10.0		10.0	ns			
t _{ACH}	Array clock high time		4.0		4.0		ns			
t _{ACL}	Array clock low time		4.0		4.0		ns			
t _{CPPW}	Minimum pulse width for clear and preset	(3)	4.0		4.0		ns			
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns			
t _{CNT}	Minimum global clock period			10.0		10.0	ns			
f _{CNT}	Maximum internal global clock frequency	(5)	100.0		100.0		MHz			
t _{ACNT}	Minimum array clock period			10.0		10.0	ns			
f _{ACNT}	Maximum internal array clock frequency	(5)	100.0		100.0		MHz			
f _{MAX}	Maximum clock frequency	(6)	125.0		125.0		MHz			

Symbol	Parameter	Conditions			Unit		
			MAX 700	OE (-10P)		00 (-10) DOE (-10)	
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.5		1.0	ns
t _{IO}	I/O input pad and buffer delay			0.5		1.0	ns
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns
t _{SEXP}	Shared expander delay			5.0		5.0	ns
t _{PEXP}	Parallel expander delay			0.8		0.8	ns
t_{LAD}	Logic array delay			5.0		5.0	ns
t _{LAC}	Logic control array delay			5.0		5.0	ns
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		1.5		2.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		2.0		2.5	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.5		6.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		5.0		5.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		5.5		5.5	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		5.0		5.0	ns
t_{SU}	Register setup time		2.0		3.0		ns
t_H	Register hold time		3.0		3.0		ns
t _{FSU}	Register setup time of fast input	(2)	3.0		3.0		ns
t_{FH}	Register hold time of fast input	(2)	0.5		0.5		ns
t _{RD}	Register delay			2.0		1.0	ns
t _{COMB}	Combinatorial delay			2.0		1.0	ns
t _{IC}	Array clock delay			5.0		5.0	ns
t_{EN}	Register enable time			5.0		5.0	ns
t _{GLOB}	Global control delay			1.0		1.0	ns
t _{PRE}	Register preset time			3.0		3.0	ns
t _{CLR}	Register clear time			3.0		3.0	ns
t_{PIA}	PIA delay			1.0		1.0	ns
t _{LPA}	Low-power adder	(8)		11.0		11.0	ns

Table 2	23. MAX 7000 & MAX 7000E Ext	ernal Timing Param	eters Note	e (1)					
Symbol	Parameter	Conditions	Speed Grade						
			MAX 700	0E (-12P)		00 (-12) DOE (-12)	-		
			Min	Max	Min	Max			
t _{PD1}	Input to non-registered output	C1 = 35 pF		12.0		12.0	ns		
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		12.0		12.0	ns		
t _{SU}	Global clock setup time		7.0		10.0		ns		
t _H	Global clock hold time		0.0		0.0		ns		
t _{FSU}	Global clock setup time of fast input	(2)	3.0		3.0		ns		
t _{FH}	Global clock hold time of fast input	(2)	0.0		0.0		ns		
t _{CO1}	Global clock to output delay	C1 = 35 pF		6.0		6.0	ns		
t _{CH}	Global clock high time		4.0		4.0		ns		
t _{CL}	Global clock low time		4.0		4.0		ns		
t _{ASU}	Array clock setup time		3.0		4.0		ns		
t _{AH}	Array clock hold time		4.0		4.0		ns		
t _{ACO1}	Array clock to output delay	C1 = 35 pF		12.0		12.0	ns		
t _{ACH}	Array clock high time		5.0		5.0		ns		
t _{ACL}	Array clock low time		5.0		5.0		ns		
t _{CPPW}	Minimum pulse width for clear and preset	(3)	5.0		5.0		ns		
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns		
t _{CNT}	Minimum global clock period			11.0		11.0	ns		
f _{CNT}	Maximum internal global clock frequency	(5)	90.9		90.9		MHz		
t _{ACNT}	Minimum array clock period			11.0		11.0	ns		
f _{ACNT}	Maximum internal array clock frequency	(5)	90.9		90.9		MHz		
f _{MAX}	Maximum clock frequency	(6)	125.0		125.0		MHz		

Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This parameter applies to MAX 7000E devices only.
- This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (6) The f_{MAX} values represent the highest frequency for pipelined data.
- (7) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 27 and 28 show the EPM7032S AC operating conditions.

Table 2	Table 27. EPM7032S External Timing Parameters (Part 1 of 2) Note (1)												
Symbol	Parameter	Conditions	Speed Grade								Unit		
			-	5	-	6	-	7	-1	10			
			Min	Max	Min	Max	Min	Max	Min	Max			
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns		
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns		
t _{SU}	Global clock setup time		2.9		4.0		5.0		7.0		ns		
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns		
t _{FSU}	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns		
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns		
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns		
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns		
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns		
t _{ASU}	Array clock setup time		0.7		0.9		1.1		2.0		ns		
t _{AH}	Array clock hold time		1.8		2.1		2.7		3.0		ns		
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns		
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns		
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns		
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns		
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns		
t _{CNT}	Minimum global clock period			5.7		7.0		8.6		10.0	ns		
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		142.9		116.3		100.0		MHz		
t _{ACNT}	Minimum array clock period			5.7		7.0		8.6		10.0	ns		

Table 27. EPM7032S External Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions				Speed	Grade	!			Unit
			-	-5 -6 -7 -10							
			Min	Max	Min	Max	Min	Max	Min	Max	
f _{ACNT}	Maximum internal array clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
f _{MAX}	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

Table 2	Table 28. EPM7032S Internal Timing Parameters Note (1)											
Symbol	Parameter	Conditions	Speed Grade									
			-5		-6		-7		-10			
			Min	Max	Min	Max	Min	Max	Min	Max	-	
t _{IN}	Input pad and buffer delay			0.2		0.2		0.3		0.5	ns	
t _{IO}	I/O input pad and buffer delay			0.2		0.2		0.3		0.5	ns	
t _{FIN}	Fast input delay			2.2		2.1		2.5		1.0	ns	
t _{SEXP}	Shared expander delay			3.1		3.8		4.6		5.0	ns	
t _{PEXP}	Parallel expander delay			0.9		1.1		1.4		0.8	ns	
t _{LAD}	Logic array delay			2.6		3.3		4.0		5.0	ns	
t _{LAC}	Logic control array delay			2.5		3.3		4.0		5.0	ns	
t _{IOE}	Internal output enable delay			0.7		0.8		1.0		2.0	ns	
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		0.4		1.5	ns	
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		0.9		2.0	ns	
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		5.4		5.5	ns	
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns	
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns	
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns	
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns	
t _{SU}	Register setup time		0.8		1.0		1.3		2.0		ns	
t _H	Register hold time		1.7		2.0		2.5		3.0		ns	
t _{FSU}	Register setup time of fast input		1.9		1.8		1.7		3.0		ns	
t _{FH}	Register hold time of fast input		0.6		0.7		0.8		0.5		ns	
t _{RD}	Register delay			1.2		1.6		1.9		2.0	ns	
t _{COMB}	Combinatorial delay			0.9		1.1		1.4		2.0	ns	
t _{IC}	Array clock delay			2.7		3.4		4.2		5.0	ns	
t _{EN}	Register enable time			2.6		3.3		4.0		5.0	ns	
t _{GLOB}	Global control delay			1.6		1.4		1.7		1.0	ns	
t _{PRE}	Register preset time			2.0		2.4		3.0		3.0	ns	
t _{CLR}	Register clear time			2.0		2.4		3.0		3.0	ns	

Symbol	Parameter	Conditions	Speed Grade									
			-5		-6		-7		-10			
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{FSU}	Register setup time of fast input		1.9		1.8		3.0		3.0		ns	
t _{FH}	Register hold time of fast input		0.6		0.7		0.5		0.5		ns	
t _{RD}	Register delay			1.2		1.6		1.0		2.0	ns	
t _{COMB}	Combinatorial delay			0.9		1.0		1.0		2.0	ns	
t _{IC}	Array clock delay			2.7		3.3		3.0		5.0	ns	
t _{EN}	Register enable time			2.6		3.2		3.0		5.0	ns	
t_{GLOB}	Global control delay			1.6		1.9		1.0		1.0	ns	
t _{PRE}	Register preset time			2.0		2.4		2.0		3.0	ns	
t _{CLR}	Register clear time			2.0		2.4		2.0		3.0	ns	
t _{PIA}	PIA delay	(7)		1.1		1.3		1.0		1.0	ns	
t_{LPA}	Low-power adder	(8)		12.0		11.0		10.0		11.0	ns	

Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Tables 31 and 32 show the EPM7128S AC operating conditions.

Table 31. EPM7128S External Timing Parameters Note (1)											
Symbol	Parameter	Conditions	Speed Grade								
			-6		-7		-10		-15		-
			Min	Max	Min	Max	Min	Max	Min	Max	1
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		3.4		6.0		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		0.9		3.0		2.0		4.0		ns
t _{AH}	Array clock hold time		1.8		2.0		5.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		3.0		4.0		6.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.8		8.0		10.0		13.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
t _{ACNT}	Minimum array clock period			6.8		8.0		10.0		13.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Notes to tables:

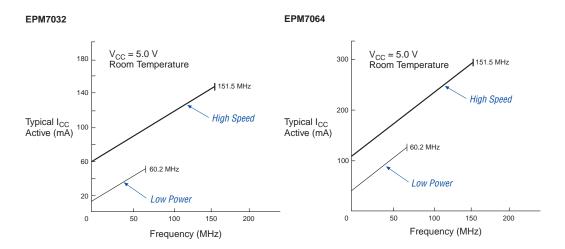
- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Tables 33 and 34 show the EPM7160S AC operating conditions.

Table 33. EPM7160S External Timing Parameters (Part 1 of 2) Note (1)											
Symbol	Parameter	Conditions Speed Grade									Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		3.4		4.2		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.9		4.8		5		8	ns
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		0.9		1.1		2.0		4.0		ns
t _{AH}	Array clock hold time		1.7		2.1		3.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.4		7.9		10.0		15.0	ns
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		3.0		4.0		6.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.7		8.2		10.0		13.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	149.3		122.0		100.0		76.9		MHz

Figure 14 shows typical supply current versus frequency for MAX 7000 devices.

Figure 14. I_{CC} vs. Frequency for MAX 7000 Devices (Part 1 of 2)



EPM7096

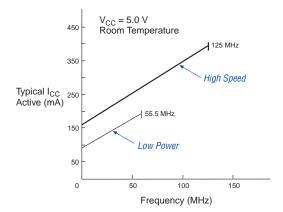
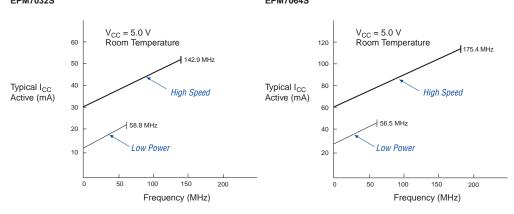


Figure 15 shows typical supply current versus frequency for MAX 7000S devices.





EPM7128S EPM7160S

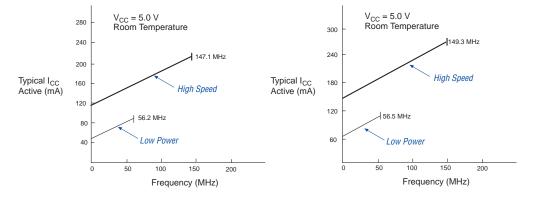
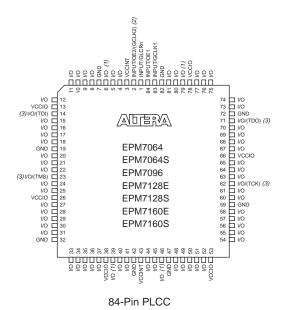


Figure 18. 84-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



Notes:

- (1) Pins 6, 39, 46, and 79 are no-connect (N.C.) pins on EPM7096, EPM7160E, and EPM7160S devices.
- (2) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (3) JTAG ports are available in MAX 7000S devices only.

